

#### **Device Features**

- Gain = 15.6 dB @ 2140MHz
- OIP3 = 35.0 dBm @ 2140 MHz
- Output P1 dB = 23.2 dBm @ 2140 MHz
- N.F = 2.9dB @ 2140 MHz
- Internally matched to 50 ohms
- RoHS2-compliant SOT-89 SMT package



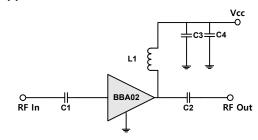
#### **Product Description**

The BBA02 is a BroadBand, GaAs E-pHEMT Amplifier that is ideal for applications demanding high linearity in a wideband of 40-8000 MHz. The BBA02 is internally matched to 50 Ohms and requires no external matching components. It is available in RoHS2-compliant SOT-89 SMT package. These devices are 100% DC and RF tested to assure quality and performance.

#### **Applications**

- Repeaters
- Mobile Infrastructure
- Defense/Aerospace
- LTE / WCDMA / EDGE / CDMA
- General Purpose Wireless
- IF amplifier, RF driver amplifier

#### **Applications Circuit**



BOM	0.04~0.5	0.5~3.0	3.0~4.0	4.0~5.0	5.0~6.0
@GHz	0.04 0.5	0.5 3.0	3.0 4.0	4.0 5.0	5.0 6.0
C1	1nF	100pF	10pF	10pF	10pF
C2	1nF	100pF	10pF	10pF	10pF
C3	100pF	100pF	100pF	100pF	100pF
C4	1nF	1nF	1nF	1nF	1nF
L1	470nH	39nH	15nH	8.2nH	4.7nH

#### **Electrical Specifications**

Device performance measured on a BeRex evaluation board at 25°C, Vd=5V, 50 Ω system.

Parameter	Conditions	Min	Тур	Max	Unit
Operational Frequency Range		40		8000	MHz
Test Frequency			2140		MHz
Gain		14.1	15.6		dB
Input Return Loss			-15.7		dB
Output Return Loss			-22.5		dB
Output IP3	5 dBm / tone , Δf=1 MHz	32.0	35.0		dBm
Output P1dB		22.2	23.2		dBm
LTE 20M ACLR*		10.5	11.5		dB
Noise Figure			2.9		dB

<sup>\*</sup>ACLR Channel Power measured at -50dBc.

#### **Recommended Operating Conditions**

Parameter	Min	Тур	Max	Unit
Bandwidth	40		8000	MHz
I <sub>d</sub> @ (V <sub>d</sub> = 5V)	72	90	108	mA
$V_d$	4.75	5.0	5.25	V
dG/dT		-0.004		dB/°C
R <sub>TH</sub>		53.5		°C/W
Operating Case Temperature	-40		+105	°C

Electrical specifications are measured at specified test conditions.

Specifications are not guaranteed over all recommended operating conditions.

#### **Absolute Maximum Ratings**

Parameter	Rating	Unit
Storage Temperature	-55 to +155	°C
Junction Temperature	+175	°C
Supply Voltage	+7	V
Supply Current	190	mA
Input RF Power	20	dBm

Operation of this device above any of these parameters may result in permanent damage.

<sup>-</sup> LTE set-up: 3GPP LTE, FDD E-TM3.1, 20MHz BW, ±20MHz offset, PAR 9.75 at 0.01% Prob.

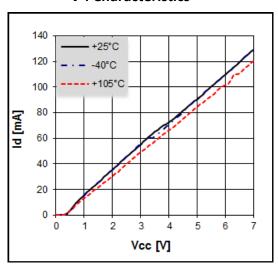


#### Typical Performance (Vd=5V, Id=90mA, T=25°C)

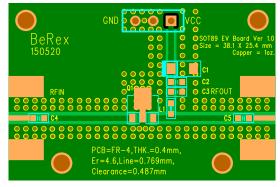
Parameter	Frequency					
	70	900	2140	3500	5800	MHz
Gain	17.2	16.6	15.6	14.5	13.5	dB
S11	-13.6	-17.0	-15.7	-12.5	-25.5	dB
S22	-15.8	-22.0	-22.5	-24.5	-28.0	dB
OIP3	36.5	38.0	35.0	33.0	28.5	dBm
P1dB	22.6	23.1	23.2	21.2	17.2	dBm
LTE 20M ACLR*	13.1	12.7	11.5	10.0	6.2	dBm
Noise Figure	2.8	2.4	2.9	3.2	5.2	dB

<sup>\*</sup>ACLR Channel Power measured at -50dBc.

#### **V-I Characteristics**



#### **BeRex SOT89 Evaluation Board**

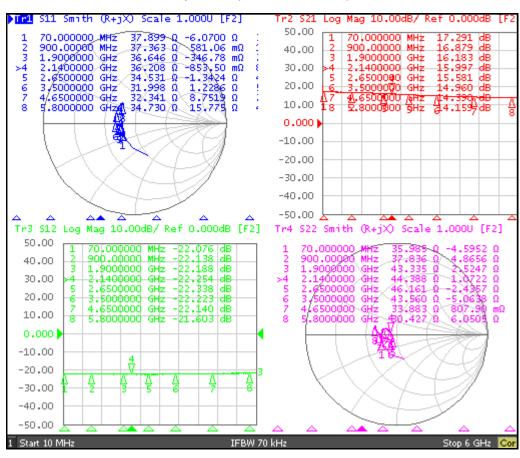


\*Dielectric constant \_ 4.6 \*RF pattern width 0.769T \*0.4T thick FR4 PCB

<sup>-</sup> LTE set-up: 3GPP LTE, FDD E-TM3.1, 20MHz BW, ±20MHz offset, PAR 9.75 at 0.01% Prob.

## **Typical Device Data**

S-parameters (Vd=5V, Id=90mA, T=25°C)



#### **S-Parameter**

(Vdevice = 5.0V, I<sub>d</sub> = 90mA, T = 25 °C, calibrated to device leads)

Freq	S11	S11	S21	S21	S12	S12	S22	S22
[MHz]	[Mag]	[Ang]	[Mag]	[Ang]	[Mag]	[Ang]	[Mag]	[Ang]
200	0.14	-170.15	7.19	169.48	0.08	-1.01	0.16	-179.43
400	0.14	-177.24	7.14	162.04	0.08	-4.60	0.16	169.63
1200	0.15	177.44	6.84	131.10	0.08	-18.57	0.13	151.36
2000	0.16	-177.38	6.39	99.93	0.08	-30.82	0.07	161.01
2800	0.19	-174.95	5.93	70.39	0.08	-45.17	0.05	-136.86
3600	0.22	172.96	5.55	42.51	0.08	-59.71	0.09	-142.84
4400	0.23	153.33	5.35	14.14	0.08	-75.21	0.17	-175.54
5200	0.25	134.61	5.04	-14.02	0.08	-94.68	0.23	164.59
6000	0.25	119.61	5.12	-44.81	0.08	-120.32	0.25	157.47

BeRex

•website: www.berex.com

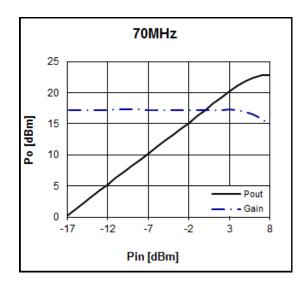
•email: sales@berex.com

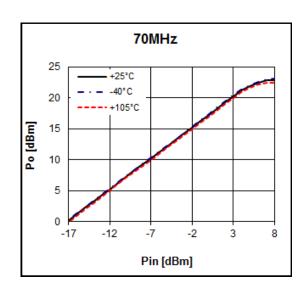


# **Application Circuit: 70 MHz**

Schematic Diagram		вом	Tolerance
C3 C4 +5V	C1	1nF	± 5%
	C2	1nF	± 5%
RFin RFout	СЗ	100pF	± 5%
C1 BBA02 (C2	C4	1nF	± 5%
<u></u>	L1	470nH	± 5%

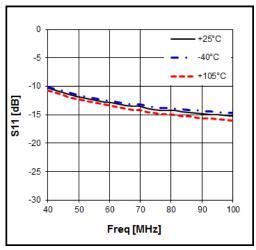
# **Typical Performance**

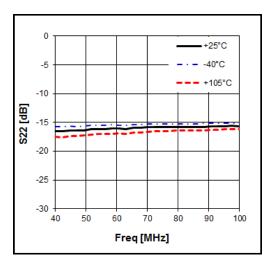


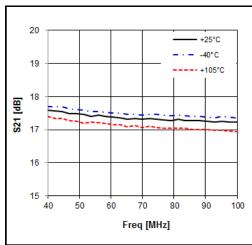


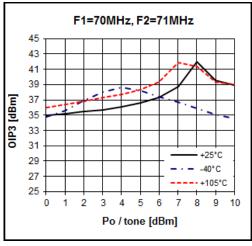


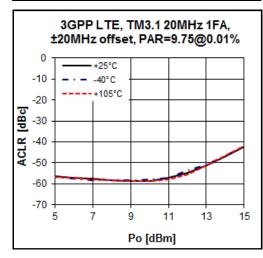


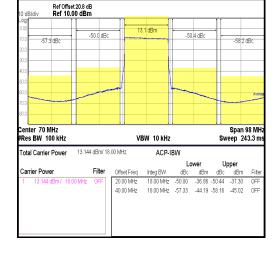










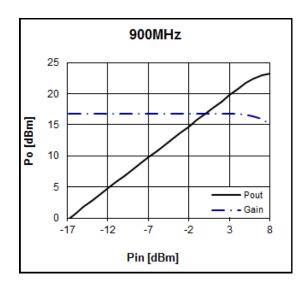


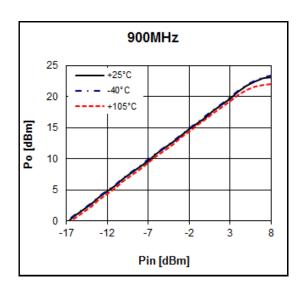


# **Application Circuit: 900 MHz**

Schematic Diagram		вом	Tolerance
C3 C4 +5V	C1	100pF	± 5%
	C2	100pF	± 5%
RFin RFout	СЗ	100pF	± 5%
C1 BBA02 (C2	C4	1nF	± 5%
	L1	39nH	± 5%

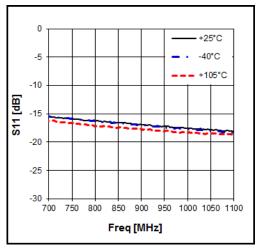
# **Typical Performance**

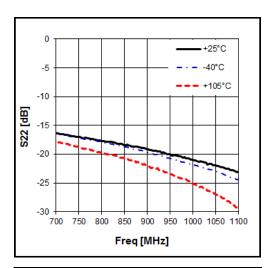


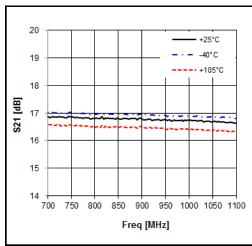


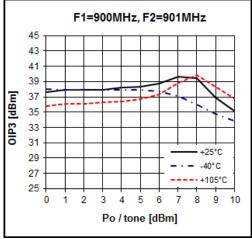


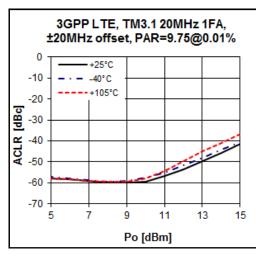


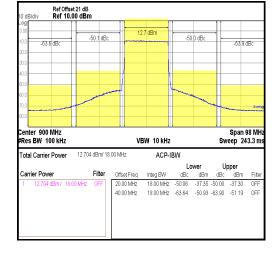










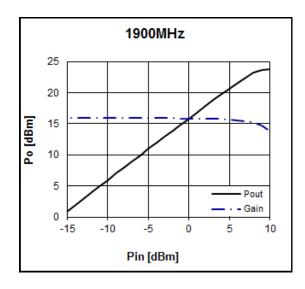


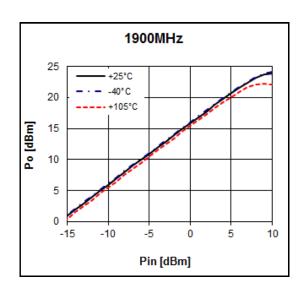


# **Application Circuit: 1900 MHz**

Schematic Diagram		вом	Tolerance
C3 C4 +5V	C1	100pF	± 5%
	C2	100pF	± 5%
RFin RFout	СЗ	100pF	± 5%
C1 BBA02 (C2	C4	1nF	± 5%
<u></u>	L1	39nH	± 5%

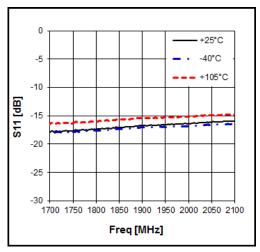
## **Typical Performance**

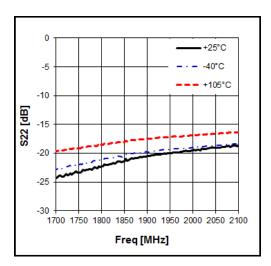


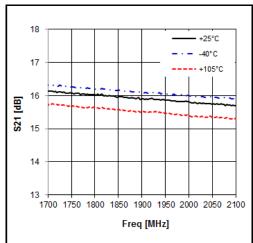


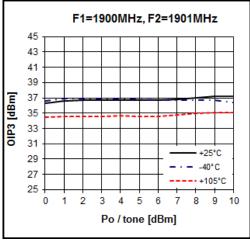


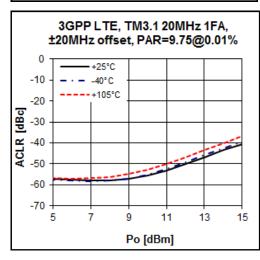


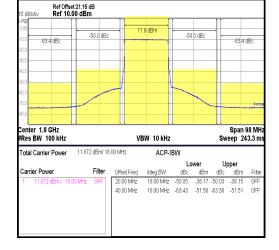










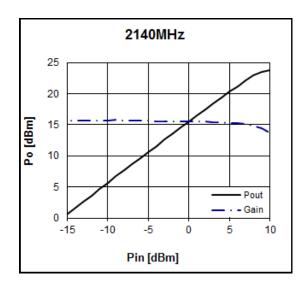


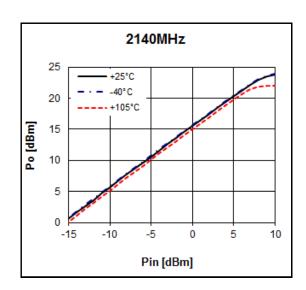


# **Application Circuit: 2140 MHz**

Schematic Diagram		вом	Tolerance
C3 C4 +5V	C1	100pF	± 5%
	C2	100pF	± 5%
RFin RFout	СЗ	100pF	± 5%
C1 BBA02 C2	C4	1nF	± 5%
<u></u>	L1	39nH	± 5%

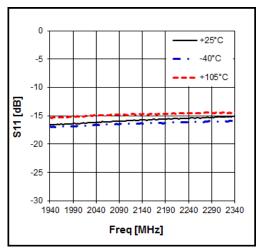
## **Typical Performance**

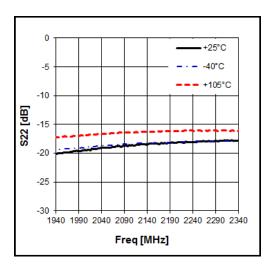


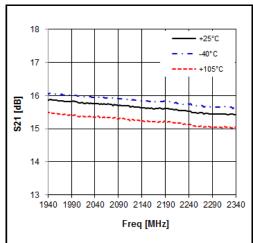


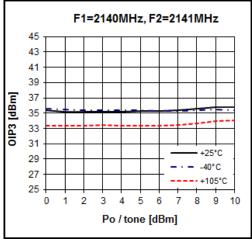


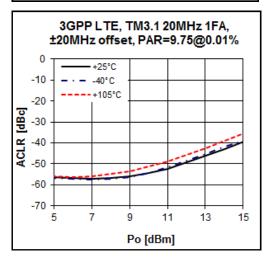


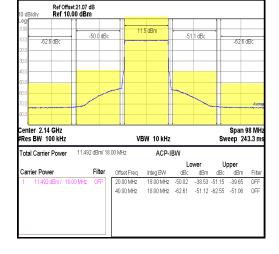










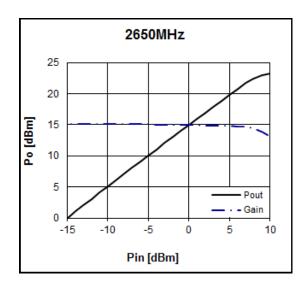


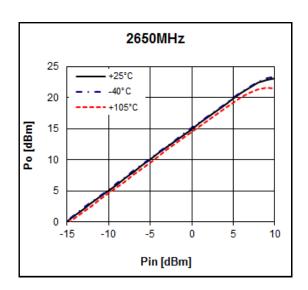


# **Application Circuit: 2650 MHz**

Schematic Diagram		вом	Tolerance
C3 C4 +5V	C1	100pF	± 5%
	C2	100pF	± 5%
RFin RFout	СЗ	100pF	± 5%
C1 BBA02 C2	C4	1nF	± 5%
<u></u>	L1	39nH	± 5%

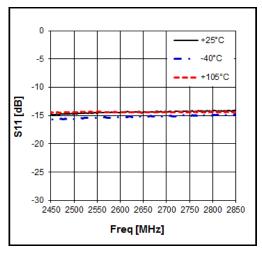
## **Typical Performance**

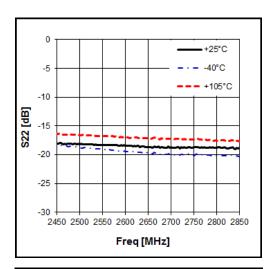


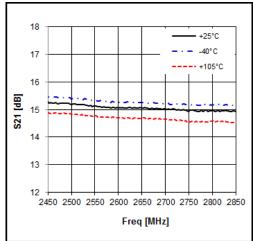


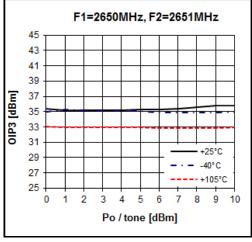


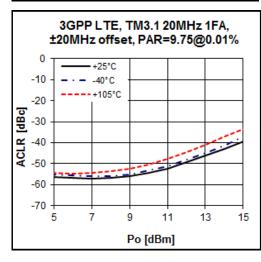


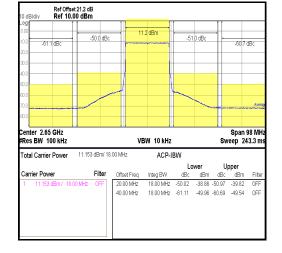










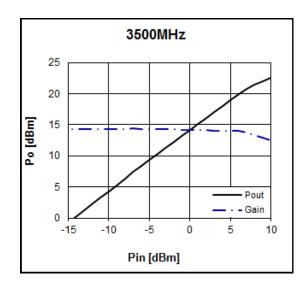


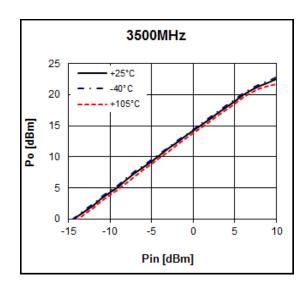


# **Application Circuit: 3500 MHz**

Schematic Diagram		вом	Tolerance
C3 C4 +5V	C1	10pF	± 5%
	C2	10pF	± 5%
RFin L1 &	С3	100pF	± 5%
C1 BBA02 (C2	C4	1nF	± 5%
<u></u>	L1	15nH	± 5%

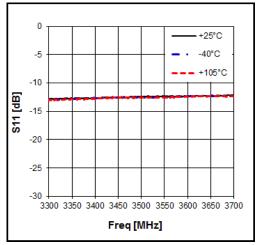
## **Typical Performance**

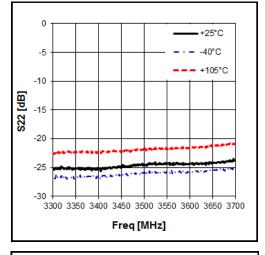


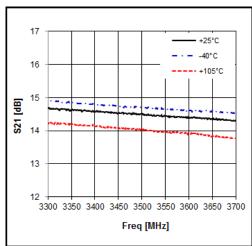


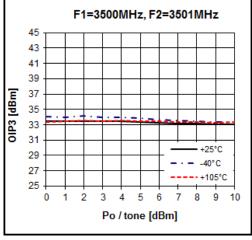


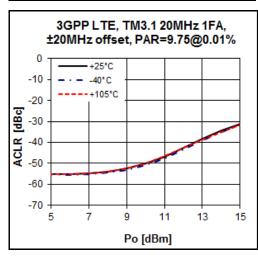


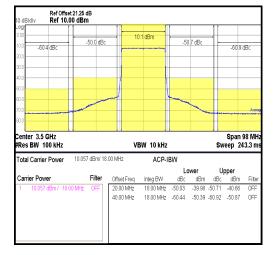










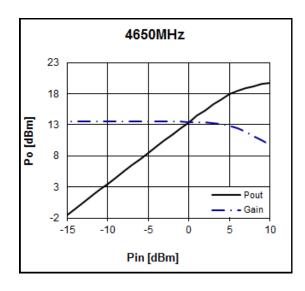


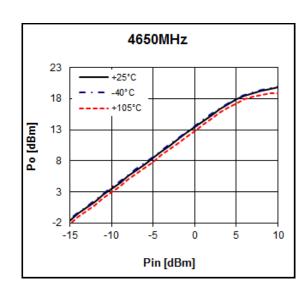


# **Application Circuit: 4650 MHz**

Schematic Diagram	ВОМ		Tolerance
C3 C4 +5V	C1	10pF	± 5%
RFin RFout	C2	10pF	± 5%
	СЗ	100pF	± 5%
C1 BBA02  ( C2	C4	1nF	± 5%
	L1	8.2nH	± 5%

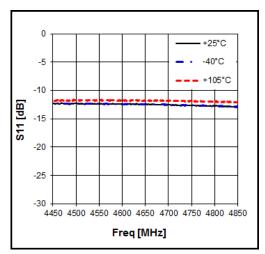
## **Typical Performance**

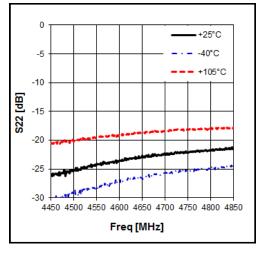


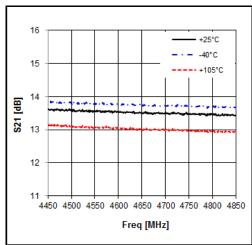


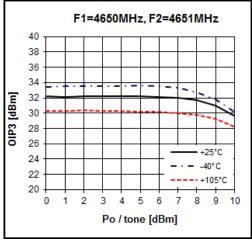


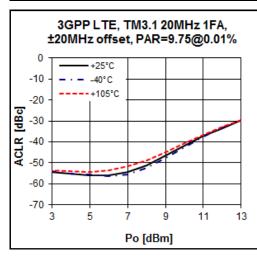


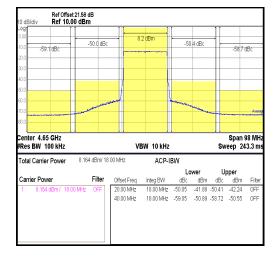










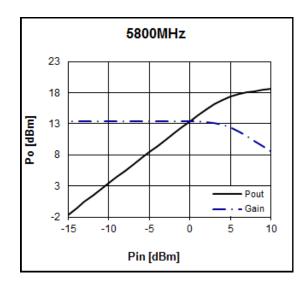


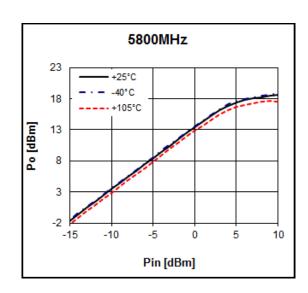


# **Application Circuit: 5800 MHz**

Schematic Diagram	ВОМ		Tolerance
C3 C4 +5V	C1	10pF	± 5%
RFin RFout	C2	10pF	± 5%
	СЗ	100pF	± 5%
C1 BBA02 (C2	C4	1nF	± 5%
	L1	4.7nH	± 5%

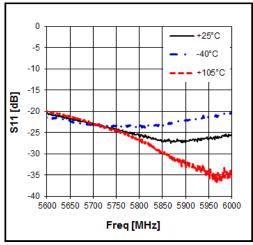
## **Typical Performance**

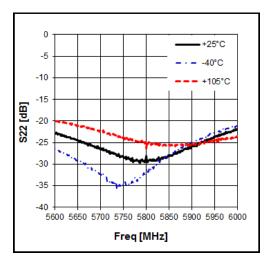


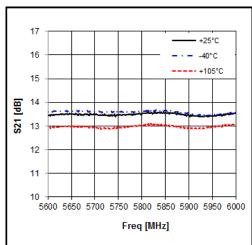


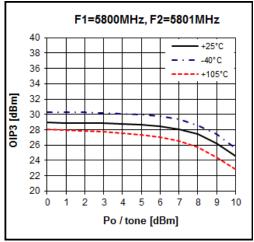


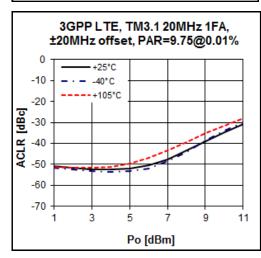


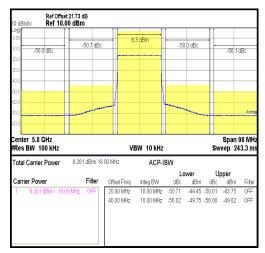






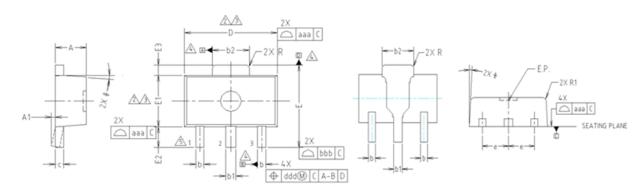








## **Package Outline Dimension**



NOTE:
1. DIMENSIONS IN MILLIMETERS.

DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED #.5mm PER END.

DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.

INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED #.5mm PER SIDE.

DIMENSIONS D AND E1 ARE DETERMINED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

A DATUMS A, B AND D TO BE DETERMINED 8.18mm FROM THE LEAD TIP.

TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

	MILLIMETERS				NOTE
SYMBOL	MINIMUM			MAXIMUM	NOTE
A	1.40	1	.50	1.60	
A1	0.00		_	0.10	
ь	0.38	0.42		0.48	
ь1	0.48	0.52		0.58	
b2	1.79	1	.82	1.87	
C	0.40	0	.42	0.46	
D	4.40	4	.50	4.70	2,3
E	3.70	4	.00	4.30	
E E1	2.40	2	.50	2.70	2,3
E2	0.80	1	.00	1.20	
E3	0.40	0	.50	0.60	
e		1.5	0 TYP.		
0			TYP.		
R	0.15 TYP.				
R1	-		_	0.20	
SYMBOL	TOLERANCES OF AND POSI	FORM TION	NOTE		
aaa	0.15				
bbb	0.20	1			
ccc	0.10				
ddd	0.10				

## **Suggested PCB Land Pattern and PAD Layout**

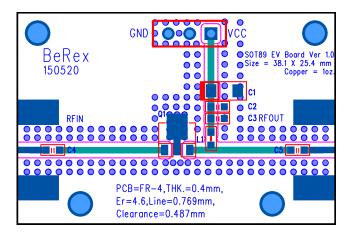
## **PCB Land Pattern**

# 

PCB lay out \_ on BeRex website

Note: All dimension millimeters

## **PCB Mounting**



BeRex

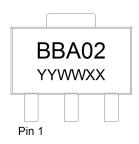
•website: www.berex.com

•email: sales@berex.com





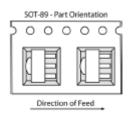
## **Package Marking**



YY = Year, WW = Working Week, XX = Wafer No.

## Tape & Reel





Packaging information:

Tape Width (mm): 12

Reel Size (inches): 7

Device Cavity Pitch (mm): 8

Devices Per Reel: 1000

## **Lead plating finish**

100% Tin Matte finish

(All BeRex products undergoes a 1 hour, 150 degree C, Anneal bake to eliminate thin whisker growth concerns.)

## MSL / ESD Rating

**ESD Rating:** Class 0

Value: Passes <200V

Test: Human Body Model (HBM)

**Standard:** JEDEC Standard JS-001-2014

MSL Rating: Level 1 at +260°C convection reflow

Standard: JEDEC Standard J-STD-020



Proper ESD procedures should be followed when handling this device.





#### **RoHS Compliance**

This part is compliant with Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS) Directive 2011/65/EU as amended by Directive 2015/863/EU. This product also is compliant with a concentration of the Substances of Very High Concern (SVHC) candidate list which are contained in a quantity of less than 0.1%(w/w) in each components of a product and/or its packaging placed on the European Community market by the BeRex and Suppliers.

#### **NATO CAGE code:**

2	N	9	6	F
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